Small Bear Project Shield

A Senior Project

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by

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ABSTRACT

The objective of the project is to design an Arduino prototype shield that resembles the Power Control Board used in the CPE 200, Small Bear Class. By designing a printed circuit board (PCB) with the same characteristics, future students will have the capability to work with a smaller, more organized power board.

Even though I’m familiar with PCB design and this is only a 2-layer board, one of the main challenges faced was learning the new software, EAGLE PCB Software. When the parts list was obtained, each component’s mechanical drawings were analyzed before drafting the schematic. The schematic design is critical since it defines the connection between the components on the board. Once the schematic was reviewed and approved, it is followed by careful placement of the component within a specified board outline and routing the connection between each node. Fabrication files were then generated. These were used in ordering the prototype boards.

Another challenge faced was time and cost. The longer it took to complete the design, the less time we had in ordering the boards. Negotiating a good price with a quick turn was necessary in order to ensure a timely arrival of the boards prior to the quarter’s end, but at the same time avoid spending a ridiculous amount of money. Shipping cost is another matter in itself. In parallel, the components were ordered online and scheduled for approximately the same arrival time as the boards. One prototype was assembled by soldering each component onto the bare PCB. The prototype shield is then mated with the Arduino UNO board, ready to be tested and programmed.
ACKNOWLEDGMENTS

I would like to thank Dr. Hugh Smith for giving me the opportunity to work on this project. Thank you for your time, help, advice, and guidance. I would also like to thank David Burke who has worked with me throughout this project, providing me the necessary input and feedback in order to obtain the requirements for a successful design. Thank you for being patient with me and answering all my questions.
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The CPE 200, Small Bear Class is an elective class taught by Dr. Hugh Smith, assisted by student David Burke. Based on Burke and Tang’s report, the objective is to design and build an animated stuffed animal. The course is divided into three sections: “power board construction, frame construction, and software development” [1]. The power board is shown in Figure 1. It was built with a protoboard, screw down headers, various through-hole components, and multiple colors of different lengths of wires. As one can imagine, the task of organizing and managing the wires alone can be quite an obstacle.

![Figure 1. Power Control Board, Version 4](image)

In the pursuit of improving the content of the class, and with the students in mind, the idea of designing a printed circuit board (PCB) was introduced. The goal is to design a PCB that performs the same function as what is shown in Figure 1. In addition, the new design shall provide an upgraded set-up to avoid unwanted situations, such as the “grounding problem,” where the “students [are] either forgetting to synchronize the grounds between the power board
or plugging it in improperly” [1]. Another problem is the “reversal of the power connector…the 9V and 5V lines have been switched, resulting in a fried Arduino board” [1]. Solutions to these problems will eliminate delays to the class and allow the students to focus on the two remaining sections.
2.1 What is a Printed Circuit Board?

According to Wikipedia, “A printed circuit board, or PCB, is used to mechanically support and electrically connect electronic components using conductive pathways, tracks or signal traces etched from copper sheets laminated onto a non-conductive substrate” [3]. In other words, it is a frame that embodies the parts used for a circuit.

For each component, or part, a footprint is laid out with copper pads that allow the parts to be soldered on to, or through, the board. The pad size and shape will vary. The footprint must fit according to the physical form of each part.

There are two types of components, classified as “surface mount” or “through-hole technology” [3]. The main difference is how they are attached to the board. With surface mount technology (SMT), the pads are placed on the top and/or bottom side of the board and components are soldered on the surface. SMT components are smaller. This type allows for a much compact and denser board, but may require automated machines for mounting the components. It’s more ideal for high volume production, but rework for defective assemblies can become a challenge.

With through-hole technology, the pads need a plated through-hole, usually in the center, where the wires or leads are inserted and soldered through the board. Though-hole components tend to be bigger than SMT components. They have “axial leads” that look like arms or “radial leads” that look like legs. This form allows hand-assembly, is likely to be more flexible, and usually easier for rework.

For connections between the components, lines are drawn, or “etched”, and embedded within the board’s body to create a route among each of the pads. This is more practical than
having multiple wires sticking out of the circuit, which can be burdensome, especially if the wires are not in complete contact with the circuit or have the tendency to get disconnected.

Overall, a PCB provides an organized structure for a circuit assembly. While the old fashion protoboards are used for testing and prototyping, PCB prototypes have become an ideal alternative.

2.2 Overview of the EAGLE PCB Design Software

Present time PCB design relies heavily on PCB design software. This is where the bulk of the design process happens. The designer applies the requirements and creates workable files for the manufacture of the board. The EAGLE PCB Design Software is used in this project.

From their website, “the name EAGLE is an acronym, which stands for Easily Applicable Graphical Layout Editor” [4]. It offers schematic layout, board layout, autorouter, and other enhanced features, depending on what version/license is installed on the computer.

I’m using the Freeware license. Because it is free software, it contains restrictions [4]:

The following limitations apply to the EAGLE Light Edition in general:

- The useable board area is limited to 100 x 80 mm (4 x 3.2 inches).
- Only two signal layers can be used (Top and Bottom).
- The schematic editor can only create one sheet.
- Support is only available via email or through our forum (no fax or phone support).
- Use is limited to non-profit applications or evaluation purposes.

Nonetheless, the EAGLE Light Edition has capabilities within the scope of this project.

One of the best part of EAGLE Light is the availability of a wide range of library of components. Upon installation, these libraries are readily accessible through the control panel (Figure 2). In other cases, when there is no good match for the component, the library editor can be used to modify existing libraries or even create a new one.
Another feature that’s worth noting on this software is its ability to link the schematic and board layout. It’s almost impossible to work with one without the other. Once a schematic design is created, a board file is also generated with it. Having both of these files open creates consistency between the schematic and PCB.

While a great portion of the time was spent learning how to use EAGLE, I won’t go too much into details since there are manuals and tutorials available to help with the software use. EAGLE has a “Training” link on their website where the user can find a good amount of learning guides, webinars, videos, and much more [4].

2.3 What is an Arduino?

Arduino is “an open-source electronics prototyping platform” [5]. It’s a “tool” that allows a user, whether it be an “inventor, designer, artist, hobbyist, [student, or] anyone interested” [5], to create projects that can interact with the “physical world” [5]. It is affordable,
can run on various operating systems, simple, and open-source both on software and hardware [5].

There are multiple types of Arduino models available. The Small Bear Project (SBP) uses the Arduino UNO, Rev. 3 (Figure 3), which operates with a “microcontroller board based on the ATmega328.” [6]. The EAGLE schematic (arduino-uno-Rev3-schematic.pdf) and reference design files (arduino-uno-Rev3-reference-design.zip) are available for download on the website [6]. These files were utilized for reference and for matching its unique board shape and size.

![Arduino UNO Board](image)

**Figure 3. Arduino UNO Board**

2.4 What is a Shield?

The purpose of this project is to design a shield for the SBP class. But what exactly is a shield? According to the Arduino website, “shields are boards that can be plugged on top of the
Arduino PCB extending its capabilities” [7]. Basically, it’s an “add-on” with a specific function. Figure 4 shows an example, a “prototype shield and a mini breadboard for use with Arduino” [8].

![Figure 4. Example: Prototype Shield + Mini Breadboard for Arduino](image)

This shield is generic, where 2 LEDs, 2 resistors, 2 switches, and numerous through-hole pads on a .100” grid are available for soldering components. It also includes a 14-pin SOIC footprint, which connects to two 2x4 header pin pads. Such shields are basic and at $4.50, are quite affordable. There hundreds of shields available at the Arduino Shield’s List website [9]. One can browse the database and attempt to find a shield suited for their project. Still, sometimes it’s better to just design your own.

The SBP Shield design will be discussed with much detail in the following sections. The project needs this shield in order to provide the current that is not attainable with the Arduino board [1].
3.1 Requirements and Information

In PCB design, before starting, it is very important to first understand what the main requirements are. A good communication between client and designer is always the key. Avoid assumptions. While it can save time, it will lead to nowhere, but delay, faulty design, and/or added cost.

I received preliminary documents from David to help me understand the concept of the Small Bear Class. I purchased an Arduino UNO board from RadioShack to have a sample of the target board, which will also be used in mating with the final assembly.

Once a rough layout of the power board (see Appendix A) was provided, David, Dr. Smith, and I had a conference call to discuss the expectations and restrictions of the component locations and to make sure I understood the information sent.

One restriction was to avoid any components that are direction on top of the Arduino USB connector. Any pins sticking out of the bottom of the SBP shield can potentially short with the USB’s metal frame. Also, in order to prevent students from any confusion on the servo lines, S1, S2, and S3 will be distinguished by female headers for S1 & S2, and male headers for S3. This is to help with polarity and avoid plugging in the connectors incorrectly. When the parts list was sent, I was able to move forward with the design.

3.2. Bill of Materials

The parts list I received included the name/description of the part, link to the online resource, and some additional notes from David, which mentions some uncertainties on what component will be used or substituted. Though it was not, yet, complete, it was workable
enough to start gathering datasheets. Throughout the project, David provided updates to finalize the list. When we realized one of the resistors was too big for the board, it was replaced with a similar resistor value, but with a smaller body size.

I used the parts list to create a Bill of Materials (BOM) (Appendix B) in order to keep me on track with the design. It was also a guide to sort out the components.

During the final process, the BOM is used to purchase the components. This document also helps with traceability of assembled components, should there be any reason to troubleshoot the shield. The cost has been added as a reference for future builds.

3.3 Component Analysis

It is important to understand the physical dimensions of each component, especially during the board layout. If the component is too large, it may result in little to no space left for routing. Using the datasheets gathered (Appendix C), the components’ mechanical information is analyzed.

For through-hole components, the key items to check is the body size and the hole size. It would be difficult to solder a through-hole component if the leads do not fit in the hole. This could lead to component rework, a search for a substitute, or even a scrapped board.

3.4 Schematic Design

In EAGLE, the designer must first add components in the schematic file by clicking the add component icon (Figure 5). The software does not allow placement on the board layout without the schematic. Everything starts at the schematic level, as it should be. Otherwise, you’d be designing blindly in the board layout.
3.4.1 Library Component Selection

A window will appear, listing all the component libraries available for use. Search or browse through to find the component that’s best suited for each item listed on the BOM. Be aware that some of these library components may appear similar to the component on the list, but in actuality, they are not. Make sure to check the actual PCB footprint and cross reference it to the datasheet mechanical dimensions to ensure the footprint is correct.

For example, as shown in Figure 6, there is the possibility of utilizing the existing component package “B3F-10XX”, found in the Switch-Omron > 10-XX library for the button switches B1 and B2.
The top right hand side of the add library window shows both the schematic symbol and the footprint. This gives us a visual of what type of component is listed. When you click ok, the schematic symbol becomes active on the schematic sheet. Left clicking the mouse places the component on the schematic sheet, along with the footprint on the board layout file. Note that with EAGLE, it is not allowed to delete the footprint on the board file. This is the software’s way of keeping the component consistent on the schematic and board file.

Switching to the board file, we see the component footprint. Using the dimension tool, we can easily make a quick check whether this is truly the footprint we want to use (Figure 7). Comparing this information to the datasheet for B1 & B2 (Figure 8), we can rely that this is a usable library component.

![Figure 7. Footprint quick check with dimension tool](image)
The rest of the components were laid out per the Table 1 below. This summarizes the components use and which library they came from.

<table>
<thead>
<tr>
<th>Item</th>
<th>Reference Designator</th>
<th>Library</th>
<th>Name</th>
<th>Description</th>
<th>Other info</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>B1,B2</td>
<td>SWITCH-OMRON</td>
<td>10-XX</td>
<td>Package: BOP-10XX Omron Switch</td>
<td>none</td>
</tr>
<tr>
<td>2</td>
<td>C1</td>
<td>RCL &gt; CPOL-US</td>
<td>CPOLUSE11-4</td>
<td>Package: E1-8-4</td>
<td>grid 1.8 mm, diameter 4 mm</td>
</tr>
<tr>
<td>3</td>
<td>C2</td>
<td>RCL &gt; C-US</td>
<td>C-US02S-040X50</td>
<td>Package: C02S-040X50</td>
<td>grid 2.5 mm, outline 4 x 5 mm</td>
</tr>
<tr>
<td>4</td>
<td>J1, JP3</td>
<td>PINHEAD</td>
<td>PINHD-1X6</td>
<td>Package: 1x06, Pin Header</td>
<td>Modified pads: was oblong, is round</td>
</tr>
<tr>
<td>5</td>
<td>J1, JP4</td>
<td>PINHEAD</td>
<td>PINHD-1X8</td>
<td>Package: 1x08, Pin Header</td>
<td>Modified pads: was oblong, is round</td>
</tr>
<tr>
<td>6</td>
<td>J2, JP2</td>
<td>PINHEAD</td>
<td>PINHD-1X10</td>
<td>Package: 1x10, Pin Header</td>
<td>Modified pads: was oblong, is round</td>
</tr>
<tr>
<td>7</td>
<td>LED1, LED2, LED3</td>
<td>LED &gt; LED</td>
<td>LED5MM</td>
<td></td>
<td>5 mm, round</td>
</tr>
<tr>
<td>8</td>
<td>MOLEX</td>
<td>COM-MOLEX</td>
<td>22-23-2041</td>
<td>Package: 22-23-2041</td>
<td>symbol, but modified pcb footprint according to datasheet</td>
</tr>
<tr>
<td>9</td>
<td>R1</td>
<td>RCL &gt; R-US</td>
<td>R-US, 2097/10</td>
<td>Package: 0207/10</td>
<td>type 0207, grid 10 mm</td>
</tr>
<tr>
<td>10</td>
<td>R2, R3</td>
<td>RCL &gt; R-US</td>
<td>R-US, 0204/7</td>
<td>Package: 0204/7</td>
<td>type 0204, grid 7.6 mm</td>
</tr>
<tr>
<td>11</td>
<td>RAIL_OFF</td>
<td>SWITCH</td>
<td>M9040P</td>
<td>Package: M9040P</td>
<td>only uses 2 pads, pin 1 no connect</td>
</tr>
<tr>
<td>12</td>
<td>S3</td>
<td>PINHEAD</td>
<td>PINHD-1X6</td>
<td>Package: 1x06, Pin Header</td>
<td>Modified pads: was oblong, is round</td>
</tr>
<tr>
<td>13</td>
<td>SEL_POWY</td>
<td>SWITCH</td>
<td>TOGGLE SWITCH</td>
<td>Package: M9040P</td>
<td></td>
</tr>
<tr>
<td>14</td>
<td>VOLT_REG</td>
<td>V-REG</td>
<td>78M00L</td>
<td>Package: 78M00L VOLTAGE REGULATOR</td>
<td>since this is stand up, removed the rest of the silk</td>
</tr>
<tr>
<td>15</td>
<td>X1</td>
<td>CON-JACK</td>
<td>DCJ0202</td>
<td>Package: DCJ0202 DC POWER JACK</td>
<td>modified location of pads</td>
</tr>
</tbody>
</table>

Table 1. Library components used and modified
While there was no need to make modifications to any of the schematic symbols, some component footprints required some changes to fit the physical part. An example will be given in Section 3.5 with details.

3.4.2 Schematic Layout

When all the library symbols have been attained, schematic design can proceed. This process went through multiple revisions (rev. P1 through P8). Although that may seem a lot, its key function is to make sure the connections are correct. An incorrect line connection can have a massive effect on the final board design outcome. For example, in the voltage regulator datasheet, it is specified in Figure 9 that the .1uF is connected at Vo.

![APPLICATION INFORMATION](image)

Figure 9. Voltage regulator application information

However, somehow, C1 and C2 were swapped on the schematic, and the capacitors were laid out incorrectly. Fortunately, during a check process, the fault was corrected prior to board manufacture.

The schematic is sent to David and Dr. Smith for final approval. See Appendix D for the final schematic.
3.5 PCB Design

When the schematic layout has been approved, we proceeded on to the PCB layout. Since the PCB footprint was already chosen during the schematic library component selection, we can proceed with placement of the components.

3.5.1 PCB Component Placement

Each footprint is placed according to Appendix A. During this process, however, placement must also be executed with respect to the airwires, or ratsnest (Figure 10). These ratsnests are a guide to show which pads should be connected. By placing the components along or near its connected pad, it makes the designer’s routing much easier. Rotating a footprint can mean drawing a simple straight trace, as oppose to drawing around the component.

The less crossing of ratsnests, the better the routing. Regardless, there will be situations when these ratsnest will still cross paths. In these occasions, we have no choice but to route through other layers of the board and maneuver the way.
Placement approval is also a necessary step prior to routing. Routing before a client approves a placement could result in wasted hours spent on the design if the client requests moving the components. During this step, Dr. Smith requested to move the X2 (Molex) connector closer to the edge of the board. With the final placement, X2 has been moved next to X1.

3.5.2 Footprint Modification

There were a few footprints from the library that did not conform to the physical dimensions of the component. The schematic symbol was used, but the footprint required some editing. For example, the 1x6 HEADER footprints used for S1, S2, and S3 originally had oblong
pads (Figure 11). The pads were changed to round shape, in order to avoid shorting when the rows are placed side by side at a .100” grid.

![Figure 11. Component footprint modification](image1)

The MOLEX footprint also did not match. The footprint was modified to almost a new footprint since the distance between each pin, the pitch, was different.

I started with a connector Molex footprint, using the KK-156-4 library package from the CON-MOLEX library. Compared to the MOLEX’s mechanical drawing’s recommended PCB hole layout, the pitch is 5.08 mm [.200”]. The existing footprint only had roughly 4.12 mm [.160”] approximately .040” off (Figure 12).

![Figure 12. MOLEX footprint modified](image2)
I increased the pitch and changed the component body outline to help determine the spaced it will occupy on the board. The outline is essential, especially for large components like these.

3.5.3 Routing

Routing is drawing the connection in the board layout to create a path between the pads. With an effective schematic, well thought out placement, and ratsnest to give guidance, the routing process did not take too long. Traces were laid out at .010” thick, which is a good line width for most boardshops. The smaller the trace, the more cost spent on the board. This applies also to drill holes. Boardshops have certain capabilities and if the board has features beyond their capabilities, we either need to find a different boardshop, or make changes to the board. This board has no limitations because it’s not too dense.

3.6 PCB Clean-up and Design Verification

Due to the many components laid out on this board, it is best to have a good silkscreen (the white markings on the board) to label the pins and components. Some reference designators were changed for clarity, e.g. X2 to MOLEX and switches to RAIL_OFF and SEL POW.

One of the most important final steps is to run EAGLE’s Design Rule Check (DRC). This is an essential check that should never be omitted. In the PCB layout, under Tools > DRC, the window opens up where the designer can specify the rules that the board must meet, like minimum clearance between copper. DRC will also check for the possibility of any shorts.
Should there be any rules not met, a summary is provided, in which the designer can have the chance to make corrections.

3.7 Gerber File Generation

When the board passed DRC, the gerber files are generated. Gerbers are the files, or the artwork, that the boardshop uses to manufacture the boards. The SBP Shield board has 8 gerber files:

- .L1 = Top Layer + Pads + Vias
- .L1S = Dimension (board outline) + tPlace + tNames (silk)
- .L2 = Bottom Layer + Pads + Vias
- .L2S = Dimension (board outline) + bPlace + bNames (silk)
- .L1M = tStop (mask layer)
- .L2M = bStop (mask layer)
- .NCD = Drills + Holes

It is good practice to open the gerber files in a gerber file viewer to review the artwork. Doing so can help you see any discrepancy on the design, if any. I used gerbv, “a free/open source gerber viewer” [10]. From this, the gerber plots were printed out to a pdf for review and approval.

3.8 Review and Approval

A final review to the schematic and gerber data is reviewed. This is the time to make any necessary changes to the board. Once everything looks good, the board is considered ready for manufacture.
3.9 Fabrication Drawing

A fabrication drawing is good to have with the gerber files since it has notes for the boardshop on what material to use and summarizes the board stack-up and drill. Unfortunately, in an effort to purchase the boards so we can receive it on time, this drawing was not created. It will be created for the next round of fabrication.

3.10 Final Gerbers and Fabrication Package

The gerber files were compressed in a .zip file. The Rev. A files do not have a fab drawing, yet, but the criteria was either specified in the board house website, email, or phone call. The zip file is sent to board houses for request for quotes (RFQ’s). If the boardhouse does not have any inquiries or request for any changes to the board, the same files are used for manufacture. Appendix E shows the gerber plots.

As an added precaution, we can request for the working gerber files from the boardhouse, prior to their manufacture. These working files are our gerber files, transferred to their system. This gives an extra step in preventing any possible oversight. These “work files” are what one would call “what you see is what you get” type of files. Boardshops will not change the artwork we submit to them, so the files should be the same.
4.1 Board House Selection

Once the design is finished, the race to find an affordable board house with a quick turn begins. The EAGLE website has a good list of them, under Services > Board Houses [11]. Due to time sensitivity, I chose board houses that are either in California or in the near states. See Appendix F for the summary.

The most ironic part about this is that the board house that quoted me the highest ($1,020.80 for a 3-day turn), ended up lower than what I expected with the most affordable $150 for 5 boards at a 3-day turn. The only caveat to it was the $101.50 shipping which is necessary for the overnight shipment. Even with the shipping cost, the confirmation to deliver within my target date was enough for me to place the order with Advanced Assembly. Chet Williams was very helpful. He really worked hard in getting me the best price possible. Sometimes, it’s beneficial to explain to the contact sales person what these prototype boards are used for and if there is a forecast for future board orders. No commitments were made to order future boards from Advanced Assembly, dealing with the same vendor will help with the re-ordering process.

Since there is no fabrication drawing, the board was manufactured in the most basic way to save on cost. Because it’s a prototype, I was not too concerned with the other factors, as long as it’s within the scope of the form, fit, and function of the design.

The board was built per the specifications: .062” thickness, FR4 material, 1 oz. copper, HASL plating, green mask LPI, and silkscreen on Top layer.
4.2 Purchasing Components

Having the BOM handy made the component purchase much easier. There is one deviation from the list that David sent me, to what was ordered. I only ordered parts from two vendors: Mouser Electronics and Sparkfun Electronics. I was able to get most of the components from these vendors, except for the R2 and R3, which was originally referenced with the Digikey website. Rather than spend an overpriced shipment for 2 pcs of resistor, I purchased an equivalent 150 ohm resistor at Mouser. It seemed like the more practical way to go.

When purchasing these items for future builds, make sure it’s given enough time to ship. The Mouser order almost didn’t arrive on time because there was a delay at the shipping center. Fortunately, I received the parts a day prior to submission, in which I was still able to assemble the prototype.

Save on cost, order ahead of time. Shipping cost can be ridiculous when turn time becomes critical.
Upon receipt of the bare boards, I first did a visual inspection to make sure it looks like the gerber files created, which it did.

The next test is what I call the bare board test in which I tested for continuity. This is to make sure the connections are present and there is no broken trace. The worst thing that can happen is to build an assembly, only to find out the board is faulty. This is not only wasteful on time, but on parts as well.

Using a multimeter (Figure 13), each pad is probed and tested. The connection were correct, except for one. It’s not related to the component, but rather the power and ground rails. There was no connection on those pads, so I must not have tied it to the ground and power. Checking the gerber plots, it’s confirmed that they were omitted. This needs to be corrected for the next board order. Regardless, this oversight does not affect the functionality of the board and is still usable. It can also be amended by soldering a blue wire from a GND pin to one of the pins on the rail. The same goes for the power pin to the power rail.

Figure 13. Bare Board Test
CHAPTER 6. ASSEMBLY

The shield is assembled by hand using a standard soldering iron (Figure 14). The components were first fitted prior to soldering.

![Assembly](image14)

Figure 14. Assembly

There are two incorrect footprints on the board. The RAIL_OFF and SEL POW had holes that were too small for the leads. Figure 15 shows the correct hole size for the switches.

![Switch hole size](image15)

Figure 15. Switch hole size
Unfortunately, I grabbed the wrong information from the NKK Switch datasheet (Figure 16).

This needs to be corrected for the next build. Fortunately, the leads of the switches can be crimped, so that I was still able to fit the leads through the hole for soldering.
The shield mated well with the Arduino board. The clearance about the USB was a good decision since it prevented any pins sticking down from hitting the USB casing. The Arduino power jack did have a slight conflict with the X1 pins directly above it. This can be amended by cutting the leads of X1 as close to the board as possible to avoid any contact below it.

After submission of the prototype to Dr. Smith and David, we found some changes are necessary to improve the spacing on the SBP Shield. See Table 2 for the summary of changes and notes for Revision B release.

The two flaws on the board were unfortunate, but not disastrous. These are also listed in Table 2. I also noticed that the SBP shield did not have any mounting holes. This was not necessary on the SBP Shield since the Arduino board already has holes, which can be used for mounting.

<table>
<thead>
<tr>
<th>Change #</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>Correct SEL_POW and RAIL_OFF footprints. Need bigger holes Ø.250”</td>
</tr>
<tr>
<td>2</td>
<td>Tie power rail to +5V and ground rail to GND</td>
</tr>
<tr>
<td>3</td>
<td>Increase annular ring pads on MOLEX</td>
</tr>
<tr>
<td>4</td>
<td>Servo headers need changing – TBD</td>
</tr>
<tr>
<td>5</td>
<td>Replace female headers on J1, J2, J3, and J4 with male headers. Plastic side to be on bottom side, solder on top of PCB. Same male header pins for S3 may possibly be used.</td>
</tr>
<tr>
<td>6</td>
<td>Move RAIL_OFF switch further away from the servo headers</td>
</tr>
<tr>
<td>7</td>
<td>Determine cost for lower switches (lower profile). Possible slider switch? -TBD</td>
</tr>
</tbody>
</table>
| 8        | Change silkscreens:  
|          | a) B1 to RESET  
|          | b) LED1 to Pin13  
|          | c) LED2 to Pwr_Rail  
|          | d) LED3 to Brd_Pwr |

Table 2. Summary of Changes for Revision B
David and I tested the SBP shield in the lab. While the results of its full functionality will have to wait until David can test it thoroughly with the Arduino board, the shield appeared to be running appropriately. The LEDs displayed the expected results, based on when power is plugged in through X1 and MOLEX. LED1 turned on when X1 was plugged in. LED2 turned on and off when RAIL_OFF was switched on and off. And LED3’s blinking which, according to David, was generated from the pin 13, with the Arduino’s default blinking program.

In conclusion, this was a great project to be involved in. I thought that because I had experience with PCB design, this would be fairly simple. However, because I was removed from my comfort zone and had to deal with a new software, it turned out to be challenging and educational. It wasn’t what I was used to, but I learned a lot, especially beyond the process of design. Purchasing and assembly allowed me to open my eyes to the difficult tasks in getting the board fabricated and assembled. Planning is very important because when time became a factor, the cost can hurt the project’s overall budget.

Figure 17. Images of the finished assembly


APPENDIX A: Rough layout of power board

Switch for board power (wall wort)

LED to show servo power

pins 0-7 extended for easy access to the right of the header

pins 8-15 extended to the right for easy access

servo connection left is 5v, mid tied to pins ranging from 2-8, right pin is made tied to ground

led tied to pin 13

PC power in (exact format undecided)

non usable due to arduino in below

switch for pc or wall wort power to servo rail

9v wall wort in via barrel jack

V reg 9->5v

LED to show power coming in

button in the middle bottom is ground -> pin 12

this just signifies solderable trace extensions for the pins near them

power section of arduino in (vin has voltage from wall wort tied to it)

signifies a line of headers for input

analog data pins translated

pin extension to translate from arduino
<table>
<thead>
<tr>
<th>Item</th>
<th>Reference Designator</th>
<th>QTY</th>
<th>Vendor</th>
<th>Vendor P/N</th>
<th>Manufacturer</th>
<th>Mfg. P/N</th>
<th>Description</th>
<th>Cost (each)</th>
<th>Cost (per assy)</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>B1, B2</td>
<td>2</td>
<td>SparkFun Electronics</td>
<td>COM-00097</td>
<td>SparkFun Electronics</td>
<td>COM-00097</td>
<td>Mini Push Button Switch, up to 50mA</td>
<td>$0.04</td>
<td>$0.07</td>
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<tr>
<td>2</td>
<td>C1</td>
<td>1</td>
<td>Mouser Electronics</td>
<td>SEA0R3M1HBK040-07</td>
<td>Lelon</td>
<td>SEA0R3M1HBK-040P</td>
<td>Aluminum Electrolytic Capacitors - Leaded 50V, 0.33uF, 20%, 4x7mm</td>
<td>$0.09</td>
<td>$0.09</td>
</tr>
<tr>
<td>3</td>
<td>C2</td>
<td>1</td>
<td>Mouser Electronics</td>
<td>81-RPER71H104K2P1A03</td>
<td>Murata Electronics</td>
<td>RPER71H104K2P1A03B</td>
<td>Multilayer Ceramic Capacitors MLCC - Leaded 0.1uF, 50V, X7R, 10%, 2.5mm L/S</td>
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<td>$0.33</td>
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<tr>
<td>4</td>
<td>J3, JP3, S1, S2</td>
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<td>SparkFun Electronics</td>
<td>PRT-09280</td>
<td>4UCON Technology Inc.</td>
<td>18688</td>
<td>Arduino Stackable Female Header, 6-PIN, .100&quot; pitch</td>
<td>$0.50</td>
<td>$2.00</td>
</tr>
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<td>5</td>
<td>J1, JP1, J4, JP4</td>
<td>4</td>
<td>SparkFun Electronics</td>
<td>PRT-09279</td>
<td>4UCON Technology Inc.</td>
<td>18688</td>
<td>Arduino Stackable Female Header, 8-PIN, .100&quot; pitch</td>
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<tr>
<td>6</td>
<td>J2, JP2</td>
<td>2</td>
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<td>PRT-11376</td>
<td>4UCON Technology Inc.</td>
<td>18688</td>
<td>Arduino Stackable Female Header, 10-PIN, .100&quot; pitch</td>
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<td>$1.00</td>
</tr>
<tr>
<td>7</td>
<td>LED1, LED2, LED3</td>
<td>3</td>
<td>Mouser Electronics</td>
<td>C503BAANCY0B025-1</td>
<td>Cree, Inc.</td>
<td>C503B-AANCY0B0251</td>
<td>Standard LEDs - Through Hole Amber Round LED</td>
<td>$0.14</td>
<td>$0.42</td>
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<tr>
<td>8</td>
<td>MOLEX</td>
<td>1</td>
<td>SparkFun Electronics</td>
<td>TOL-11300</td>
<td>Molex</td>
<td>SDA-8981-4V</td>
<td>Molex Connector - Straight, Vertical Mount, 4-PIN, .200&quot; pitch</td>
<td>$0.95</td>
<td>$0.95</td>
</tr>
<tr>
<td>9</td>
<td>R1</td>
<td>1</td>
<td>Mouser Electronics</td>
<td>271-350-RC</td>
<td>Xicon</td>
<td>271-350-RC</td>
<td>Metal Film Resistors - Through Hole 350ohms, 1% 50PPM</td>
<td>$0.13</td>
<td>$0.13</td>
</tr>
<tr>
<td>10</td>
<td>R2, R3</td>
<td>2</td>
<td>Mouser Electronics</td>
<td>660-CFS1/4CTS2R151J</td>
<td>KOA Speer</td>
<td>CFS1/4CTS2R151J</td>
<td>Carbon Film Resistors - Through Hole 150 OHM 5% 1/4W</td>
<td>$0.15</td>
<td>$0.30</td>
</tr>
<tr>
<td>11</td>
<td>RAIL_OFF</td>
<td>1</td>
<td>Mouser Electronics</td>
<td>108-0001-EVX</td>
<td>Mountain Switch</td>
<td>108-0001-EVX</td>
<td>Toggle Switches SPST OFF-ON</td>
<td>$3.27</td>
<td>$3.27</td>
</tr>
<tr>
<td>12</td>
<td>S3</td>
<td>0.15</td>
<td>SparkFun Electronics</td>
<td>PRT-00116</td>
<td>Pololu Robotics &amp; Electronics, or equivalent</td>
<td>965, or equivalent</td>
<td>Breakaway Male Header, 1x40-Pin, Straight, .100&quot; pitch</td>
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<td>$0.23</td>
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<tr>
<td>13</td>
<td>SEL.Pow</td>
<td>1</td>
<td>Mouser Electronics</td>
<td>633-M201201</td>
<td>NKK Switches</td>
<td>M2012SS1W01</td>
<td>Toggle Switches ON-NONE-ON SPDT</td>
<td>$2.75</td>
<td>$2.75</td>
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<tr>
<td>14</td>
<td>VOLT_REG</td>
<td>1</td>
<td>Mouser Electronics</td>
<td>595-UA7805CKCS</td>
<td>Texas Instruments</td>
<td>UA7805CKCS</td>
<td>Linear Regulators - Standard Positive V</td>
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<td>15</td>
<td>X1</td>
<td>1</td>
<td>SparkFun Electronics</td>
<td>PRT-10811</td>
<td>4UCON Technology Inc.</td>
<td>18742</td>
<td>DC Barrel Jack Adapter - Breadboard Compatibile</td>
<td>$0.95</td>
<td>$0.95</td>
</tr>
</tbody>
</table>

**TOTAL** $13.85
SEA Series

Features
- 85°C, 2,000 hours assured, standard miniature type with 7mm height for compact circuits
- RoHS Compliance

Specifications

<table>
<thead>
<tr>
<th>Items</th>
<th>Performance</th>
</tr>
</thead>
<tbody>
<tr>
<td>Category Temperature Range</td>
<td>-40°C ~ +85°C</td>
</tr>
<tr>
<td>Capacitance Tolerance</td>
<td>±20%</td>
</tr>
<tr>
<td>Leakage Current (at 20°C)</td>
<td>I = 0.01fC/V or 3 (A) whichever is greater (after 2 minutes)</td>
</tr>
<tr>
<td>Where, C = rated capacitance in F, V = rated DC working voltage in V</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Rated Voltage</th>
<th>4</th>
<th>6.3</th>
<th>10</th>
<th>16</th>
<th>25</th>
<th>35</th>
<th>50</th>
<th>63</th>
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</thead>
<tbody>
<tr>
<td>Tan (max)</td>
<td>0.35</td>
<td>0.23</td>
<td>0.20</td>
<td>0.16</td>
<td>0.14</td>
<td>0.12</td>
<td>0.10</td>
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Low Temperature Characteristics (at 120Hz)

<table>
<thead>
<tr>
<th>Impedance Ratio</th>
<th>4</th>
<th>6.3</th>
<th>10</th>
<th>16</th>
<th>25</th>
<th>35</th>
<th>50</th>
<th>63</th>
</tr>
</thead>
<tbody>
<tr>
<td>Z (±25°C)/Z (±20°C)</td>
<td>7</td>
<td>4</td>
<td>3</td>
<td>3</td>
<td>2</td>
<td>2</td>
<td>2</td>
<td>2</td>
</tr>
<tr>
<td>Z (±40°C)/Z (±20°C)</td>
<td>14</td>
<td>10</td>
<td>8</td>
<td>6</td>
<td>4</td>
<td>4</td>
<td>4</td>
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Endurance

<table>
<thead>
<tr>
<th>Test Time</th>
<th>2,000 hrs</th>
</tr>
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<tbody>
<tr>
<td>Capacitance Change</td>
<td>Within 200% of initial value</td>
</tr>
<tr>
<td>Tan</td>
<td>Less than 200% of specified value</td>
</tr>
<tr>
<td>Leakage Current</td>
<td>Within specified value</td>
</tr>
</tbody>
</table>

* The above Specifications shall be satisfied when the capacitors are restored to 20°C after the rated voltage applied with rated ripple current for 20,000 hours at 85°C.

Shelf Life Test

Test time: 500 hours, other items are the same as those for the Endurance.

Ripple Current & Frequency Multipliers

<table>
<thead>
<tr>
<th>F (Hz)</th>
<th>60 (50)</th>
<th>120</th>
<th>500</th>
<th>1k</th>
<th>10k up</th>
</tr>
</thead>
<tbody>
<tr>
<td>Under 47</td>
<td>0.70</td>
<td>1.00</td>
<td>1.20</td>
<td>1.30</td>
<td>1.45</td>
</tr>
<tr>
<td>100 to 1,000</td>
<td>0.60</td>
<td>1.00</td>
<td>1.10</td>
<td>1.15</td>
<td>1.20</td>
</tr>
</tbody>
</table>

Diagram of Dimensions

[Diagram of Dimensions]

Lead Spacing and Diameter

<table>
<thead>
<tr>
<th>Unit: mm</th>
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<tbody>
<tr>
<td>φ D</td>
</tr>
<tr>
<td>d</td>
</tr>
<tr>
<td>α</td>
</tr>
<tr>
<td>β</td>
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</table>

Dimension & Permissible Ripple Current

<table>
<thead>
<tr>
<th>F (Hz)</th>
<th>4V (5G)</th>
<th>6.3V (1G)</th>
<th>10V (1A)</th>
<th>16V (1C)</th>
<th>25V (1E)</th>
<th>35V (1V)</th>
<th>50V (1H)</th>
<th>63V (1J)</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>0.10</td>
<td>0.10</td>
<td>0.10</td>
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<td>0.10</td>
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<td>2.2</td>
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<td>2R2</td>
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<td>2R2</td>
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<td>102</td>
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</tbody>
</table>

Ripple Current: mA/ms at 120 Hz, 85°C

Part Numbering System

<table>
<thead>
<tr>
<th>SEA series</th>
<th>470 F</th>
<th>±20%</th>
<th>6.3V Bulk Package</th>
<th>Gas Type</th>
<th>8φ×7L</th>
<th>Pb-free and PET coating case</th>
</tr>
</thead>
<tbody>
<tr>
<td>Series</td>
<td>Capacitance</td>
<td>Capacitance</td>
<td>Rated Voltage</td>
<td>Lead Configuration &amp; Package</td>
<td>Rubber Type</td>
<td>Case Size</td>
</tr>
</tbody>
</table>

Note: For more details, please refer to "Part Numbering System (Radial Type)" on page 10.

All product specifications in the catalog are subject to change without notice. (CAT. 2013E1)
Radial Lead Type
Monolithic Ceramic Capacitors
Part Numbering

Radial Lead Type Monolithic Ceramic Capacitors

(Part Number)  

Product ID  
Series/Terminal

<table>
<thead>
<tr>
<th>Product ID</th>
<th>Series/Terminal</th>
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<tbody>
<tr>
<td>RP</td>
<td>Radial Lead Type Monolithic Ceramic Capacitors (DC25V-DC100V)</td>
</tr>
<tr>
<td>RH</td>
<td>Radial Lead Type Monolithic Ceramic Capacitors (DC50V-DC100V)</td>
</tr>
<tr>
<td>RD</td>
<td>Radial Lead Type Monolithic Ceramic Capacitors (For Commercial Use Only) (DC25V-DC630V)</td>
</tr>
</tbody>
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Temperature Characteristics

<table>
<thead>
<tr>
<th>Code</th>
<th>Temperature Characteristics</th>
<th>Reference Temperature</th>
<th>Temperature Range</th>
<th>Capacitance Change or Temperature Coefficient</th>
<th>Operating Temperature Range</th>
</tr>
</thead>
<tbody>
<tr>
<td>5C</td>
<td>C0G</td>
<td>25°C</td>
<td>25 to 125°C</td>
<td>0±30ppm/°C</td>
<td>-55 to 125°C</td>
</tr>
<tr>
<td>5G</td>
<td>X8G</td>
<td>25°C</td>
<td>25 to 150°C</td>
<td>0±30ppm/°C</td>
<td>-55 to 150°C</td>
</tr>
<tr>
<td>C7</td>
<td>X7S</td>
<td>25°C</td>
<td>-55 to 125°C</td>
<td>±22%</td>
<td>-55 to 125°C</td>
</tr>
<tr>
<td>D7</td>
<td>X7F</td>
<td>25°C</td>
<td>-55 to 125°C</td>
<td>±22% -33%</td>
<td>-55 to 125°C</td>
</tr>
<tr>
<td>F1</td>
<td>F</td>
<td>20°C</td>
<td>-25 to 85°C</td>
<td>±30 -80%</td>
<td>-25 to 85°C</td>
</tr>
<tr>
<td>F5</td>
<td>Y9V</td>
<td>25°C</td>
<td>-30 to 85°C</td>
<td>+22 -52%</td>
<td>-30 to 85°C</td>
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<tr>
<td>L8</td>
<td>X8L</td>
<td>25°C</td>
<td>125 to 150°C</td>
<td>±15%</td>
<td>-55 to 150°C</td>
</tr>
<tr>
<td>R7</td>
<td>X7R</td>
<td>25°C</td>
<td>-55 to 125°C</td>
<td>±15%</td>
<td>-55 to 125°C</td>
</tr>
</tbody>
</table>

*Please refer to table for Capacitance change under reference temperature.

Capacitance change from each temperature

<table>
<thead>
<tr>
<th>Char.</th>
<th>Nominal Values (ppm/°C) *1</th>
<th>Capacitance Change from 25°C (%)</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>0±30</td>
<td>-55°C Max.</td>
</tr>
<tr>
<td>C0G</td>
<td>0.58</td>
<td>-0.24</td>
</tr>
<tr>
<td>X8G</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

*1: Nominal values denote the temperature coefficient within a range of 25 to 125°C.

Rated Voltage

<table>
<thead>
<tr>
<th>Code</th>
<th>Rated Voltage</th>
</tr>
</thead>
<tbody>
<tr>
<td>1E</td>
<td>DC25V</td>
</tr>
<tr>
<td>1H</td>
<td>DC50V</td>
</tr>
<tr>
<td>2A</td>
<td>DC100V</td>
</tr>
<tr>
<td>2E</td>
<td>DC250V</td>
</tr>
<tr>
<td>2W</td>
<td>DC450V</td>
</tr>
<tr>
<td>2J</td>
<td>DC630V</td>
</tr>
</tbody>
</table>

Capacitance

Expressed by three-digit alphanumerics. The unit is pico-farad (pF). The first and second figures are significant digits, and the third figure expresses the number of zeros that follow the two numbers.

If there is a decimal point, it is expressed by the capital letter "R".

In this case, all figures are significant digits.

Capacitance Tolerance

<table>
<thead>
<tr>
<th>Code</th>
<th>Capacitance Tolerance</th>
<th>Temperature Characteristics</th>
<th>Capacitance Step</th>
</tr>
</thead>
<tbody>
<tr>
<td>C</td>
<td>±0.25pF</td>
<td>C0G</td>
<td>±5pF, ±1pF Step</td>
</tr>
<tr>
<td>D</td>
<td>±0.5pF</td>
<td>X8G/6pF</td>
<td>±10pF, ±5pF Step</td>
</tr>
<tr>
<td>J</td>
<td>±0.5%</td>
<td>X8G</td>
<td>±10. E 12 Series</td>
</tr>
<tr>
<td>K</td>
<td>±10%</td>
<td>X75/7T/X7R/X8L</td>
<td>E6 Series</td>
</tr>
<tr>
<td>M</td>
<td>±20%</td>
<td>X8L</td>
<td>E3 Series</td>
</tr>
<tr>
<td>Z</td>
<td>±80%, ±20%</td>
<td>F/Y9V</td>
<td>E3 Series</td>
</tr>
</tbody>
</table>

Continued on the following page.
Individual Specification Code
Expressed by three-digit alphanumerics

Packaging

Dimensions (LxW)

<table>
<thead>
<tr>
<th>Code</th>
<th>Dimensions (LxW)</th>
</tr>
</thead>
<tbody>
<tr>
<td>0</td>
<td>4.0X3.5mm or 5.0X3.5mm (Depends on Part Number List)</td>
</tr>
<tr>
<td>1</td>
<td>4.0X3.5mm or 4.5X3.5mm or 5.0X3.5mm (Depends on Part Number List)</td>
</tr>
<tr>
<td>2</td>
<td>5.0X4.5mm or 5.5X4.0mm or 5.7X4.0mm (Depends on Part Number List)</td>
</tr>
<tr>
<td>3</td>
<td>5.0X4.5mm or 5.5X5.0mm or 6.0X5.0mm (Depends on Part Number List)</td>
</tr>
<tr>
<td>5</td>
<td>7.5X7.5mm</td>
</tr>
<tr>
<td>6</td>
<td>10.0X10.0mm</td>
</tr>
<tr>
<td>7</td>
<td>12.5X12.5mm</td>
</tr>
<tr>
<td>8</td>
<td>7.5X7.5mm</td>
</tr>
<tr>
<td>U</td>
<td>7.7X12.5mm</td>
</tr>
<tr>
<td>W</td>
<td>5.5X7.5mm</td>
</tr>
</tbody>
</table>

DC630V: W+0.5mm

Lead Style

<table>
<thead>
<tr>
<th>Code</th>
<th>Lead Style</th>
<th>Lead Spacing</th>
</tr>
</thead>
<tbody>
<tr>
<td>A2</td>
<td>Straight Long</td>
<td>2.5mm</td>
</tr>
<tr>
<td>B1</td>
<td>Straight Long</td>
<td>5.0mm</td>
</tr>
<tr>
<td>C1</td>
<td>Straight Long</td>
<td>10.0mm</td>
</tr>
<tr>
<td>DB</td>
<td>Straight Taping</td>
<td>2.5mm</td>
</tr>
<tr>
<td>E1/E2</td>
<td>Straight Taping</td>
<td>5.0mm</td>
</tr>
<tr>
<td>K1</td>
<td>Inside Crimp</td>
<td>5.0mm</td>
</tr>
<tr>
<td>M1/M2</td>
<td>Inside Crimp Taping</td>
<td>5.0mm</td>
</tr>
<tr>
<td>P1</td>
<td>Outside Crimp</td>
<td>2.5mm</td>
</tr>
<tr>
<td>S1/S2</td>
<td>Outside Crimp Taping</td>
<td>2.5mm</td>
</tr>
</tbody>
</table>

Lead distance between reference and bottom planes:
- M1, S1: H0 = 16.0±0.5mm
- M2, S2: H0 = 20.0±0.5mm
- E1: H = 17.5±0.5mm
- E2: H = 20.0±0.5mm
SPECIFICATIONS
Current Rating: 3Amp
Contact Resistance: 20 Milliohms Max.
Insulation Resistance: 1000 Megohms Min.
Withstand Voltage: 1000V AC/Minute
Operation Temperature: -40°C to +105°C
Contact: Brass, Gold Plated Over Nickel
Insulator: Polyester (UL94V-0)
Standard: PBT+30%G.F
MECHANICAL DIMENSIONS

All dimensions are in mm. Tolerance is ±0.25 mm unless otherwise noted.

An epoxy meniscus may extend about 1.5 mm down the leads.

Burr around bottom of epoxy may be 0.5 mm max.

---

NOTES

RoHS Compliance

The levels of environmentally sensitive, persistent biologically toxic (PBT), persistent organic pollutants (POP), or otherwise restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2002/95/EC on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS), as amended through April 21, 2006.

Vision Advisory Claim

Users should be cautioned not to stare at the light of this LED product. The bright light can damage the eye.
MECHANICAL DIMENSIONS

All dimensions are in mm. Tolerance is ±0.25 mm unless otherwise noted.

An epoxy meniscus may extend about 1.5 mm down the leads.

Burr around bottom of epoxy may be 0.5 mm max.

C503B-RAN/AAN/RCN:

C503B-RBN/ABN:

C503B-ACN:

NOTES

RoHS Compliance

The levels of environmentally sensitive, persistent biologically toxic (PBT), persistent organic pollutants (POP), or otherwise restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2002/95/EC on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS), as amended through April 21, 2006.

Vision Advisory Claim

Users should be cautioned not to stare at the light of this LED product. The bright light can damage the eye.
**KIT NUMBER SYSTEM**

All dimensions in mm. Cree LED lamps are tested and sorted into performance bins. A bin is specified by ranges of color, forward voltage, and brightness. Sorted LEDs are packaged for shipping in various convenient options. Please refer to the “Cree LED Lamp Packaging Standard” document for more information about shipping and packaging options.

Cree LEDs are sold by order codes in combinations of bins called kits. Order codes are configured in the following manner:

- **Product Series (CCCC)**
- **Color (D)**
- **Option (G)**
  - S: Standoff
  - N: No Standoff
  - B: Black Face
  - W: White Face
  - A: Black Body
- **Packaging Type (T)**
  - 1: Bulk Pack
  - 2: Ammo Pack
  - 3: Tape & Reel (Roll Pack)
  - 4: Tube Pack
- **Maximum Wavelength/Chromaticity Range (N)**
- **Minimum Wavelength/Chromaticity Range (M)**
- **Maximum Intensity Bin (KK)**
- **Minimum Intensity Bin (HH)**
RECOMMENDED PCB HOLE LAYOUT

NOTES:
1. PART TO MATE WITH HOUSING 8981-4P AND TERMINAL 8980-24.
2. PRODUCT SPEC. PS-8981-4V+ APPLIES
3. PARTS TO BE PACKED IN MOISTURE BARRIER BAG.

MATERIAL:
HOUSING: NYLON 6/6, UNFILLED. 94V-2. COLOR - NATURAL (OFF-WHITE).
TERMINAL: PHOSPHOR BRONZE, C51000
PLATING: POSTPLATE 10-150/.0000100 MIN., TIN OVER 101-121/.000050 MIN., NICKEL OVERALL

ADD NOTE 3.

QUALITY SYMBOLS:

<table>
<thead>
<tr>
<th>GENERAL TOLERANCES (UNLESS SPECIFIED)</th>
<th>MM/IN</th>
</tr>
</thead>
<tbody>
<tr>
<td>DRAWN BY DATE</td>
<td></td>
</tr>
<tr>
<td>TAY 1989/05/26</td>
<td></td>
</tr>
<tr>
<td>NIK 1989/05/26</td>
<td></td>
</tr>
<tr>
<td>1989/05/26</td>
<td></td>
</tr>
</tbody>
</table>

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS
Metal Film Fixed Resistors (RoHS Compliant)  

**FEATURES**  
- Temperature Range: -55°C ~ +155°C  
- ±1% tolerance  
- Epoxy coated miniature resistors  
- Nickel chromium ceramic substrate  
- Alloy coated leads  
- Welded end caps  
- EIA standard color coding

**LOAD LIFE**

![Graph showing ΔR/R (%) vs Nominal Resistance (Ω)]

**DERATING CURVE**

![Graph showing Percent Rated Load vs Ambient Temperature (°C)]

**PART NUMBERING SYSTEM**

270 - 100 / REEL - RC

- **Series**: 270
- **Ohms**: 100
- **Package Code**: REEL
- **Suffix (RoHS Compliant)**: RC

**SERIES, WATTAGE, SIZE, VOLTAGE, DIMENSIONS, AND AVAILABLE PACKAGING**

<table>
<thead>
<tr>
<th>Series</th>
<th>Watts</th>
<th>Standard Range of Values (Ω)</th>
<th>Voltage (max.)</th>
<th>Dimensions (mm)</th>
<th>Standard Quantities Available</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td>W.V.</td>
<td>O.V.</td>
<td>L max.</td>
<td>D max.</td>
</tr>
<tr>
<td>270</td>
<td>1/8</td>
<td>1~10M</td>
<td>200</td>
<td>400</td>
<td>3.5</td>
</tr>
<tr>
<td>271</td>
<td>1/4</td>
<td>1~10M</td>
<td>250</td>
<td>500</td>
<td>6.8</td>
</tr>
<tr>
<td>273</td>
<td>1/2</td>
<td>1~10M</td>
<td>350</td>
<td>700</td>
<td>10</td>
</tr>
</tbody>
</table>

XC-600046  
Date Revised: 9/28/05

Specifications are subject to change without notice. No liability or warranty implied by this information. Environmental compliance based on producer documentation.
features

- Flameproof coating is available (specify “CFP”)
- Reduced body size (specify “CFS/CFPS”)
- Suitable for automatic machine insertion
- Marking: Venetian red with color-coded bands on CF
  Green body color with color-coded bands on CFP
  Ivory body color with color-coded bands on CFS1/4
- Products with lead-free terminations meet EU RoHS and China RoHS requirements

dimensions and construction

ordering information

New Part # 1/4 C T52 R 103 J
Type CF CFP CF CFP CF CFP CF CFP CF CFP
Power Rating S1/4: 0.25W 1/4: 0.25W S1/2: 0.5W C: SnCu Axial: T26, T52, L52 Radial: VT, MT, MHT, VTP, VTE U Forming: U, UCL M Forming: M5, M10, M12.5 L Forming: L10, L12.5
Taping and Forming
Packaging A: Ammo R: Reel
Nominal Resistance 2 significant figures + 1 multiplier
Tolerance *R* indicates decimal on value <10Ω
G: ±2%
J: ±5%

For further information on packaging, please refer to Appendix C.

Specifications given herein may be changed at any time without prior notice. Please confirm technical specifications before you order and/or use.
applications and ratings

<table>
<thead>
<tr>
<th>Part Designation</th>
<th>Power Rating @ 70°C</th>
<th>Minimum Dielectric Withstanding Voltage</th>
<th>T.C.R. (ppm/°C)</th>
<th>Resistance Range E-24 (Ω±2%)</th>
<th>Resistance Range E-24 (Ω±5%)</th>
<th>Absolute Maximum Working Voltage</th>
<th>Absolute Maximum Overload Voltage</th>
</tr>
</thead>
<tbody>
<tr>
<td>CFS1/4</td>
<td>0.25W</td>
<td>2.2Ω - 47kΩ</td>
<td>±3$\times$10^{-5}$</td>
<td>10Ω - 330kΩ</td>
<td>2.2Ω - 5.1MΩ</td>
<td>250V</td>
<td>500V</td>
</tr>
<tr>
<td>CFPS1/4</td>
<td></td>
<td>110kΩ - 330kΩ</td>
<td>1Ω - 1MΩ</td>
<td>10Ω - 100kΩ</td>
<td>2.2Ω - 1MΩ</td>
<td>300V</td>
<td>600V</td>
</tr>
<tr>
<td>CF1/4</td>
<td>0.50W</td>
<td>2.2Ω - 100kΩ</td>
<td>2.2Ω - 5.1MΩ</td>
<td>2.2Ω - 1MΩ</td>
<td>350V</td>
<td>700V</td>
<td></td>
</tr>
<tr>
<td>CFPS1/2</td>
<td></td>
<td>110kΩ - 330kΩ</td>
<td>2.2Ω - 100kΩ</td>
<td>2.2Ω - 1MΩ</td>
<td>350V</td>
<td>700V</td>
<td></td>
</tr>
<tr>
<td>CF1/2</td>
<td></td>
<td>100kΩ - 1MΩ</td>
<td>±350Ω</td>
<td>51kΩ - 100kΩ</td>
<td>2.2Ω - 1MΩ</td>
<td>300V</td>
<td>600V</td>
</tr>
<tr>
<td>CFPS1/2</td>
<td></td>
<td>100kΩ - 1MΩ</td>
<td>±1Ω - 2.2MΩ</td>
<td>2.2Ω - 1MΩ</td>
<td>350V</td>
<td>700V</td>
<td></td>
</tr>
</tbody>
</table>

Operating temperature: -55°C – +155°C

Derating Curve

Surface Temperature Rise

Load Life @ 70°C, 1000 Hr

For resistors operated at an ambient temperature of 70°C or above, a power rating shall be derated in accordance with the above derating curve.

Performance Characteristics

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Requirement Limit</th>
<th>Δ R (% ± 0.05Ω) Typical</th>
<th>Test Method</th>
</tr>
</thead>
<tbody>
<tr>
<td>Resistance</td>
<td>Within specified tolerance</td>
<td>—</td>
<td>Measuring points are at 10mm ±1mm from the end cap.</td>
</tr>
<tr>
<td>T.C.R.</td>
<td>Within specified T.C.R.</td>
<td>—</td>
<td>Room temperature +100°C</td>
</tr>
<tr>
<td>Overload (Short time)</td>
<td>±1%</td>
<td>±0.5%</td>
<td>Rated voltage x 2.5 or max. overload voltage for 5 seconds, whichever is lower</td>
</tr>
<tr>
<td>Resistance to Solder Heat</td>
<td>±1%</td>
<td>±0.5%</td>
<td>260°C ±5°C, 10 seconds ± 1 second</td>
</tr>
<tr>
<td>Terminal Strength</td>
<td>No lead-coming off and loose terminals</td>
<td>—</td>
<td>Twist 360°C, 5 times</td>
</tr>
<tr>
<td>Rapid Change of Temperature</td>
<td>±1%</td>
<td>±0.5%</td>
<td>-55°C (30 minutes), +125°C (30 minutes), 5 cycles</td>
</tr>
<tr>
<td>Moisture Resistance</td>
<td>±5%</td>
<td>±2.5%</td>
<td>40°C ± 2°C, 90 - 95% RH, 1000 hours, 1.5 hr ON, 0.5 hr OFF cycle</td>
</tr>
<tr>
<td>Endurance at 70°C</td>
<td>±3%</td>
<td>±1.5%</td>
<td>70°C ± 2°C, 1000 hours, 1.5 hr ON, 0.5 hr OFF cycle</td>
</tr>
<tr>
<td>Resistance to Solvent (CFS &amp; CFPS only)</td>
<td>No abnormality in appearance. Marking shall be easily legible.</td>
<td>—</td>
<td>Ultrasonic washing with Isopropyl alcohol for 2 minutes. Power: 0.3W/cm², f: 28kHz, temp: 35°C±5°C</td>
</tr>
<tr>
<td>Flame Retardant (CFS &amp; CFPS only)</td>
<td>No evidence of flaming or self-flaming</td>
<td>—</td>
<td>Flame test: The test flame shall be applied and removed for each 15 seconds respectively to repeat the cycle 5 times. Overload flame retardant: Power (AC) corresponding to 2, 4, 8, 16 and 32 times the power rating shall be applied for each minute until disconnection occurs. However the applied voltage shall not exceed 4 times the maximum operating voltage.</td>
</tr>
</tbody>
</table>
**Dimensions: mm (in.)**

- **Keyway:**
  - (0.50) 12.70
  - (0.27) 6.86

- **Panel Mounting**

  - **Without locking ring:**
    - (0.033) 0.85
    - (0.022) 0.55

  - **With standard locking ring:**
    - (0.24) 6.10
    - (0.094) 2.38

- **Solder Lug**

  - Epoxy seal
    - (0.047) 1.19
    - (0.08) 2.03

  - (0.156) 3.96

**Electrical Specifications:**
- Rating: 2A / 250VAC, 5A / 120 VAC or 28 VDC
- Contact Resistance: 10mΩ max. initial @ 2-4VDC 100mA
- Insulation Resistance: 1,000MΩ min.
- Dielectric Strength: 1,000 V RMS@sea level

**Mechanical Specifications:**
- Mechanical Life: 40,000 make-and-break cycles
- Operating Temperature: -30°C to 85°C
- Type: SPST
- Circuit: On-Off

**Materials:**
- Case: Diallyl phthalate (DAP)
- Actuator: Brass, chrome plated
- Bushing: Brass, nickel plated
- Housing: Stainless Steel
- Terminal/Contact: Silver or gold plated

**Note:**
- RoHS compliant by exemption

**Miniature Toggle Switch**

108-0001-EVX

Available from Mouser Electronics

www.mouser.com 1-800-346-6873

Specifications are subject to change without notice. No liability or warranty implied by this information. Environmental compliance based on producer documentation.
Bushing Mount Miniature Toggles

CONTACT MATERIALS & RATINGS

<table>
<thead>
<tr>
<th></th>
<th>Power Level</th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>W</td>
<td>Silver over Silver</td>
<td>6A @ 125V AC &amp; 3A @ 250V AC</td>
</tr>
<tr>
<td>G</td>
<td>Gold over Brass or Copper</td>
<td>6A @ 125V AC &amp; 3A @ 250V AC</td>
</tr>
</tbody>
</table>

Note: See Supplement section to find complete explanation of operating range.

A | Gold over Silver | Power Level or Logic Level | 6A @ 125V AC or 0.4VA maximum @ 28V AC/DC maximum |

Note: This dual rated option is suitable when two or more identical switches are used in logic and in power circuits within the same application. See Supplement section to find complete explanation of dual rating and operating range.

TERMINALS

<table>
<thead>
<tr>
<th></th>
<th>Description</th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>01</td>
<td>Solder Lug</td>
<td></td>
</tr>
<tr>
<td>02</td>
<td>.062” (1.57mm) Wide Quick Connect</td>
<td></td>
</tr>
<tr>
<td>03</td>
<td>.250” (6.35mm) Straight PC</td>
<td></td>
</tr>
<tr>
<td>05</td>
<td>.425” (10.8mm) Wirewrap or Extended PC</td>
<td></td>
</tr>
<tr>
<td>06</td>
<td>.750” (19.05mm) Wirewrap or Extended PC</td>
<td></td>
</tr>
<tr>
<td>07</td>
<td>.964” (24.5mm) Wirewrap or Extended PC</td>
<td></td>
</tr>
<tr>
<td>08</td>
<td>1.062” (27.0mm) Wirewrap or Extended PC</td>
<td></td>
</tr>
</tbody>
</table>

If using as extended PC terminal, refer to the above footprints.

OPTIONAL CAPS & CAP COLORS

<table>
<thead>
<tr>
<th></th>
<th>Description</th>
<th>Material:</th>
</tr>
</thead>
<tbody>
<tr>
<td>B</td>
<td>AT415 Lever Cap for S Bat Toggle</td>
<td>Polyethylene</td>
</tr>
<tr>
<td>C</td>
<td>AT444 Conical Cap for S Bat Toggle</td>
<td>Polyethylene</td>
</tr>
<tr>
<td>R</td>
<td>AT434 Lever Cap for B Toggle</td>
<td>Polyvinyl Chloride</td>
</tr>
<tr>
<td>V</td>
<td>AT406 Lever Cap for B2 Toggle</td>
<td>Polyvinyl Chloride</td>
</tr>
</tbody>
</table>

Cap Colors Available: A Black  B White  C Red  E Yellow  F Green  G Blue
TYPICAL SWITCH DIMENSIONS

**Solder Lug**

![Solder Lug Single Pole](image1)

M2012SS1W01

**Solder Lug**

![Solder Lug Double Pole](image2)

M2022SS1W01

**Solder Lug**

![Solder Lug Three Pole](image3)

M2032SS1W01

**Solder Lug**

![Solder Lug Four Pole](image4)

M2042SS1W01

**Single Pole**

![Single Pole](image5)

M2011 model does not have terminal 1.

**Double Pole**

![Double Pole](image6)

M2021 model does not have terminals 1 & 4.

**Three Pole**

![Three Pole](image7)

**Four Pole**

![Four Pole](image8)
µA7800 SERIES

SLVS056O—MAY 1976—REVISED AUGUST 2012

www.ti.com

µA7824 Electrical Characteristics (continued)
at specified virtual junction temperature, \( V_J = 33 \, \text{V}, \, I_J = 500 \, \text{mA} \) (unless otherwise noted)

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITIONS</th>
<th>( T_J ) ( ^{(1)} )</th>
<th>( \mu A7824 )</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td></td>
<td>( \begin{array}{ccc} \text{MIN} &amp; \text{TYP} &amp; \text{MAX} \end{array} )</td>
<td></td>
</tr>
<tr>
<td>Output voltage regulation</td>
<td>( I_O = 5 , \text{mA} ) to 1.5 A</td>
<td>25°C</td>
<td>12</td>
<td>480</td>
</tr>
<tr>
<td></td>
<td>( I_O = 250 , \text{mA} ) to 750 mA</td>
<td></td>
<td>4</td>
<td>240</td>
</tr>
<tr>
<td>Output resistance</td>
<td>( f = 1 , \text{kHz} )</td>
<td>0°C to 125°C</td>
<td>0.028</td>
<td>( \Omega )</td>
</tr>
<tr>
<td>Temperature coefficient of output voltage</td>
<td>( I_O = 5 , \text{mA} )</td>
<td>0°C to 125°C</td>
<td>-1.5</td>
<td>( \mu \text{V/°C} )</td>
</tr>
<tr>
<td>Output noise voltage</td>
<td>( f = 10 , \text{Hz} ) to 100 kHz</td>
<td>25°C</td>
<td>170</td>
<td>( \mu \text{V} )</td>
</tr>
<tr>
<td>Dropout voltage</td>
<td>( I_O = 1 , \text{A} )</td>
<td>25°C</td>
<td>2</td>
<td>( \text{V} )</td>
</tr>
<tr>
<td>Bias current</td>
<td></td>
<td>25°C</td>
<td>4.6</td>
<td>8</td>
</tr>
<tr>
<td>Bias current change</td>
<td>( V_I = 27 , \text{V} ) to 38 V</td>
<td>0°C to 125°C</td>
<td>1</td>
<td>( \text{mA} )</td>
</tr>
<tr>
<td></td>
<td>( I_O = 5 , \text{mA} ) to 1 A</td>
<td></td>
<td>0.5</td>
<td></td>
</tr>
<tr>
<td>Short-circuit output current</td>
<td></td>
<td>25°C</td>
<td>150</td>
<td>( \text{mA} )</td>
</tr>
<tr>
<td>Peak output current</td>
<td></td>
<td>25°C</td>
<td>2.1</td>
<td>( \text{A} )</td>
</tr>
</tbody>
</table>

APPLICATION INFORMATION

Figure 2. Fixed-Output Regulator

Figure 3. Positive Regulator in Negative Configuration (\( V_I \) Must Float)

Figure 4. Adjustable-Output Regulator

A: The following formula is used when \( V_{xx} \) is the nominal output voltage (output to common) of the fixed regulator:

\[
V_O = V_{xx} + \left( \frac{V_{xx}}{R1} + I_O \right)R2
\]

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NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Lead dimensions are not controlled within this area.
D. All lead dimensions apply before solder dip.
E. The center lead is in electrical contact with the mounting tab.
F. The chamfer is optional.
G. Thermal pad contour optional within these dimensions.
H. Falls within JEDEC TO-220 variation AB, except minimum lead thickness, minimum exposed pad length, and maximum body length.
SPECIFICATION
Rating: DC 20V 4A
Contact Resistance: 30 Milliamps Max.
Insulation Resistance: 100 Megaohms Min. (DC 500V)
Withstand Voltage: 500V AC
Insertion And Extraction Force: 3~30N
Life Test: 5000 Cycles
Operation Temperature Range: -20°C~+70°C
Preservative Temperature Range: -40°C~+85°C
RoHS Compliant
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## APPENDIX F - BOARD HOUSE QUOTES

<table>
<thead>
<tr>
<th>Board House</th>
<th>QTY</th>
<th>Price Each</th>
<th>NRE</th>
<th>TOTAL</th>
<th>Lead Time</th>
<th>Dock Date</th>
<th>Notes</th>
<th>E-mail Contact</th>
</tr>
</thead>
<tbody>
<tr>
<td>Custom Circuit Boards</td>
<td>5</td>
<td>$90.00</td>
<td></td>
<td>$450.00</td>
<td>3-days</td>
<td></td>
<td>RFQ sent 6/4 via website</td>
<td>Tom White <a href="mailto:tw@customcircuitboards.com">tw@customcircuitboards.com</a></td>
</tr>
<tr>
<td>Custom Circuit Boards</td>
<td>10</td>
<td>$46.80</td>
<td></td>
<td>$468.00</td>
<td>3-days</td>
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<td>Tom White <a href="mailto:tw@customcircuitboards.com">tw@customcircuitboards.com</a></td>
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<td>Custom Circuit Boards</td>
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<td></td>
<td>$550.00</td>
<td>3-days</td>
<td></td>
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<td>Tom White <a href="mailto:tw@customcircuitboards.com">tw@customcircuitboards.com</a></td>
</tr>
<tr>
<td>OnBoard Circuits</td>
<td>5</td>
<td>$675</td>
<td></td>
<td>$675</td>
<td>3-days</td>
<td></td>
<td>RFQ sent 6/4 via website</td>
<td>Yvonne Banovich <a href="mailto:yvonne@onboardcircuits.com">yvonne@onboardcircuits.com</a></td>
</tr>
<tr>
<td>Photo Fabricators Inc.</td>
<td></td>
<td></td>
<td></td>
<td>$500</td>
<td>3-days</td>
<td></td>
<td>RFQ sent 6/4 via website (broken link, gerber no upload)</td>
<td></td>
</tr>
<tr>
<td>Fineline Circuits &amp; Technology</td>
<td>5</td>
<td>$500</td>
<td>$400</td>
<td>$400</td>
<td>3-days</td>
<td></td>
<td>RFQ sent 6/4 via website (no gbrs)</td>
<td>R. Bajaria <a href="mailto:rbajaria@finelinecircuits.com">rbajaria@finelinecircuits.com</a></td>
</tr>
<tr>
<td>Printed Circuit Solutions, Inc. (Select Circuits)</td>
<td></td>
<td></td>
<td></td>
<td>$450</td>
<td>5-days</td>
<td>6/11/13</td>
<td>RFQ sent 6/4 via email attach (<a href="mailto:quotes@actpcb.com">quotes@actpcb.com</a>)</td>
<td>Andy Butani <a href="mailto:andy@actpcb.com">andy@actpcb.com</a></td>
</tr>
<tr>
<td>American Circuit Technology</td>
<td>5</td>
<td>$31.04</td>
<td>Included</td>
<td>$155.20</td>
<td>3-days</td>
<td>Starting Wed, 6/10</td>
<td>RFQ online</td>
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</tr>
<tr>
<td>Sierra Proto Express</td>
<td>5</td>
<td>$162.07</td>
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<td>$630.35</td>
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<td></td>
<td>RFQ online</td>
<td></td>
</tr>
<tr>
<td>Advanced Assembly</td>
<td>5</td>
<td>--</td>
<td>--</td>
<td>$1,020.80</td>
<td>3-days</td>
<td></td>
<td>RFQ sent 6/4 via website upload; 6/4 nope, Chet Williams <a href="mailto:chet@aapcb.com">chet@aapcb.com</a></td>
<td></td>
</tr>
<tr>
<td>Advanced Assembly</td>
<td>5</td>
<td>--</td>
<td>--</td>
<td>$245 +</td>
<td>5-days</td>
<td>6/11/2013</td>
<td>6/5 new quote, Chet is willing to work with Chet Williams <a href="mailto:chet@aapcb.com">chet@aapcb.com</a></td>
<td></td>
</tr>
<tr>
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<td>$658.35</td>
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</tbody>
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Summary of Functional Requirements
The Small Bear Project Shield is an upgrade of the Power Control Board used in the Small Bear Project class, which utilizes the printed circuit board technology for a smaller structure. It has a connector that receives a 9V power through a wall wart, converted to 5V with a voltage regulator. It also has a connector to plug in a computer power supply. The power source is selected with a switch. The assembled board is used to power a stuffed animal bear that is built and programmed in the class.

Primary Constraints
The main challenge was to learn the EAGLE software. Maneuvering through the schematic, board, and library editor consumed a majority of the time allotted for the design. Another challenge was purchasing the boards and components. Time and cost were the limiting factor. Time was very limited upon approval of the design. Finding the right boardhouse that can manufacture the board with a quick turn at a low cost proved to be challenging. The same goes with ordering the components.

Economic
Original estimated cost for board and component parts: approx. $300
Actual final cost of board and component parts: $280.35 for 5 pcbs, components, and shipping
Bill of materials for component parts is included in the report.
Additional costs: $34.99 Arduino and $4.95 Prototype Shield used for reference.
All software used are freeware.
Original estimated development time: one quarter
Actual development time: one quarter for the final assembly build. Time for testing the shield with the Arduino is variable.

If manufactured on a commercial basis: Not Applicable

Environmental
Components are attached on the board by means soldering. Solder contains tin and lead. Lead is a chemical known to be toxic. Any scrapped components can also have an environmental impact if not disposed of accordingly.

Manufacturability
Purchasing: It’s a challenge to find the right boardshop that can produce a good quality board at a low price, especially on the first run. For future builds, availability of components will be a challenge.
Assembly: Soldering the components can be difficult for anyone who has not soldered before.

Sustainability
Maintaining: The shield contains components that are electrostatic-sensitive device (ESD). Proper care for storage and handling should be followed accordingly to avoid damage.
Project impacts the sustainable use of resources: uses many components for the assembly
Upgrades: Smaller component can be used as an alternative in order to keep the height to a minimum.
Issues with upgrading: Changing components can require a redesign of the component footprint
• Ethical
  The only ethical issue relating to the design is disposal. Electronic equipment should be disposed of appropriately in order to avoid toxic waste to the environment.

• Health and Safety
  During assembly, soldering produces fumes that can cause risk to one’s health. Students assembling the boards should be in an environment with good ventilation. Students shall wear protective eyewear. Soldering irons is hot and proper soldering etiquette should be followed.

• Social and Political: Not applicable.

• Developmental
  Discovering the open-source software, especially the EAGLE software, expanded my vision for future hobby projects. The availability of resources on the EAGLE website was very valuable. And learning beyond the process of design, extending to purchasing and manufacturing, increased my appreciation for those other departments.